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April 18, 2003

DUPLICATE
COPY

To: Examiner Michael Luhrs
USPTO
Art Unit 2824
FAX: 703-746-7473

From: George SimionYour Ref.: 09/843,924Our Ref.: 109182Number of Pages Sent (Including cover sheet): 6Prepared By: gps**Comments:**

Examiner Luhrs,

I have enclosed a copy of the Second Supplemental Amendment filed in the USPTO today, April 18.

Please call if you have any questions regarding the Second Supplemental Amendment.

Thank you.

George Simion

Sent by: gps

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PATENT APPLICATION**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924

Examiner: Michael K. Luhrs

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD
FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE

SECOND SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

As supplement to the Supplemental Amendment filed April 11, 2003, please further
amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 1:

1. (Twice Amended) A method for forming a bump, comprising:
forming a resist layer that defines a through hole which overlaps at least a
portion of a pad;
forming an opening in an insulating film after forming the resist layer, the
opening exposing at least a part of the pad; and
forming a metal layer constituting a bump after forming the opening, the metal
layer connected to the portion of the pad exposed at the opening.